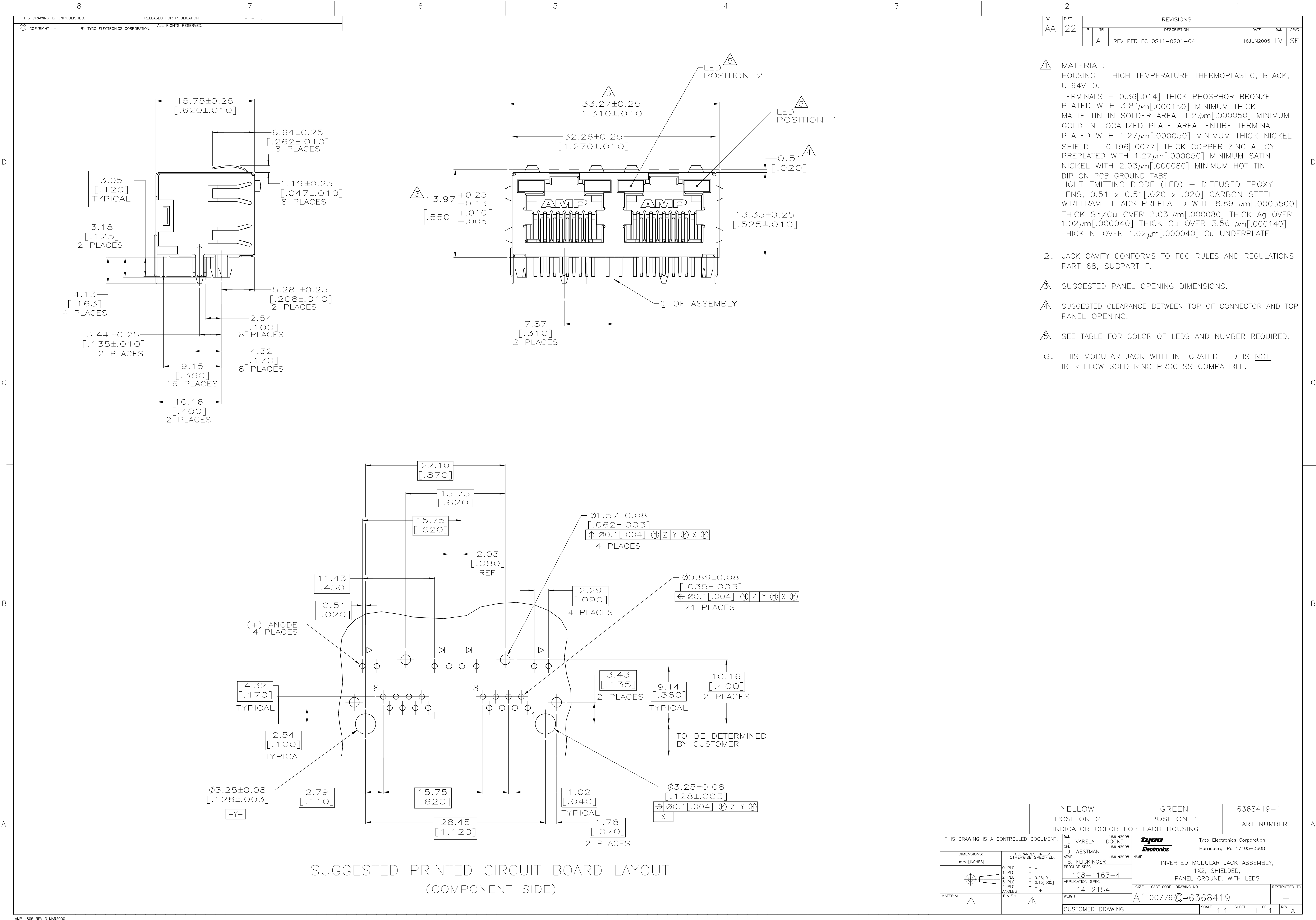




LOC		DIST		REVISIONS					
AA		22		P	LTR	DESCRIPTION	DATE	DWN	APVD
					A	REV PER EC 0S11-0201-04	16JUN2005	LV	SF

MATERIAL:

HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.

TERMINALS - 0.36[.014] THICK PHOSPHOR BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27µm[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MINIMUM THICK NICKEL.

SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.

LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 µm[.0003500] THICK Sn/Cu OVER 2.03 µm[.000080] THICK Ag OVER 1.02µm[.000040] THICK Cu OVER 3.56 µm[.000140] THICK Ni OVER 1.02 µm[.000040] Cu UNDERPLATE

2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.

SUGGESTED PANEL OPENING DIMENSIONS.

SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.

SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.

THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.

YELLOW	GREEN	6368419-1
POSITION 2	POSITION 1	PART NUMBER
INDICATOR COLOR FOR EACH HOUSING		

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN L. VARELA - DOCKS CHK J. WESTMAN	16JUN2005 16JUN2005	Tyco Electronics Corporation Harrisburg, Pa 17105-3608	
DIMENSIONS: mm [INCHES]		APVD S. FLICKINGER	16JUN2005	NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC	108-1163-4	INVERTED MODULAR JACK ASSEMBLY, 1X2, SHIELDED, PANEL GROUND, WITH LEDS	
0 PLC ± -		APPLICATION SPEC	114-2154	SIZE	
1 PLC ± -		WEIGHT	-	CAGE CODE	
2 PLC ± 0.25(.01)		DRAWING NO		RESTRICTED TO	
3 PLC ± 0.13(.005)		SCALE		1:1	
4 PLC ± -		SHEET		1 OF 1	
ANGLES		REV		A	
FINISH		CUSTOMER DRAWING			